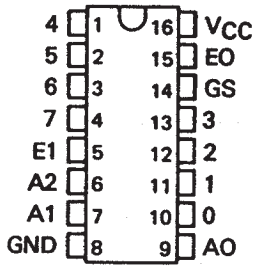
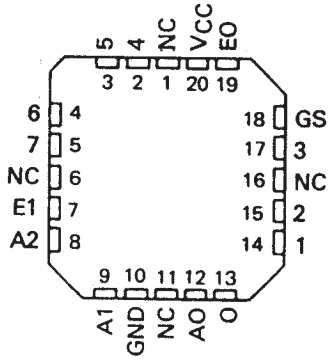
- 3-State Outputs Drive Bus Lines Directly
- Encodes 8 Data Lines to 3-Line Binary (Octal)
- Applications Include:
  - N-Bit Encoding
  - Code Converters and Generators
- Typical Data Delay . . . 15 ns
- Typical Power Dissipation . . . 60 mW

SN54LS348 . . . J OR W PACKAGE
SN74LS348 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS348 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

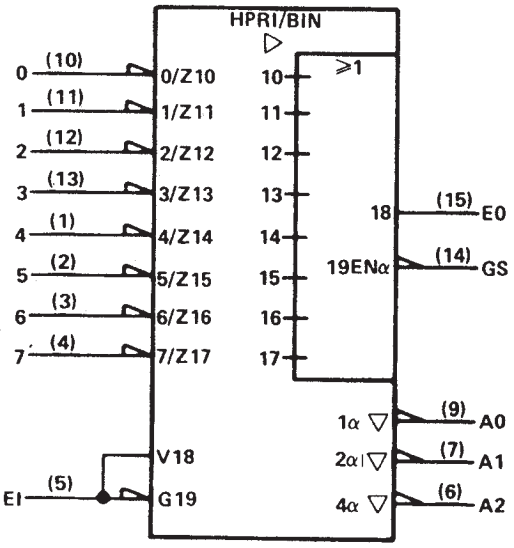
These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The 'LS348 circuits encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input E1 and enable output EO) has been provided to allow octal expansion. Outputs A0, A1, and A2 are implemented in three-state logic for easy expansion up to 64 lines without the need for external circuitry. See Typical Application Data.

FUNCTION TABLE

INPUTS									OUTPUTS				
EI	0	1	2	3	4	5	6	7	A2	A1	A0	GS	EO
H	X	X	X	X	X	X	X	X	Z	Z	Z	H	H
L	H	H	H	H	H	H	H	H	Z	Z	Z	H	L
L	X	X	X	X	X	X	X	L	L	L	L	L	H
L	X	X	X	X	X	X	L	H	L	L	H	L	H
L	X	X	X	X	X	L	H	H	L	H	L	L	H
L	X	X	X	X	L	H	H	H	L	H	H	L	H
L	X	X	X	L	H	H	H	H	H	L	L	L	H
L	X	X	L	H	H	H	H	H	H	L	H	L	H
L	X	L	H	H	H	H	H	H	H	H	L	L	H
L	L	H	H	H	H	H	H	H	H	H	H	L	H

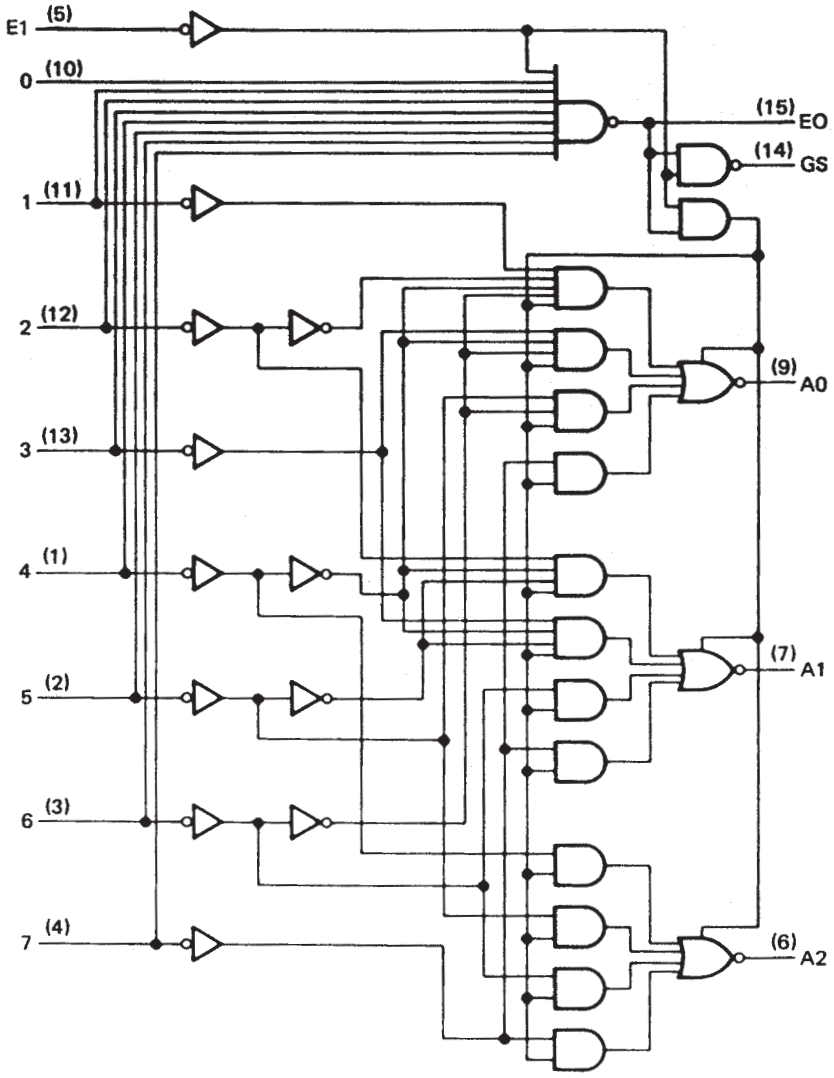
H = high logic level, L = low logic level, X = irrelevant
Z = high-impedance state

logic symbol†



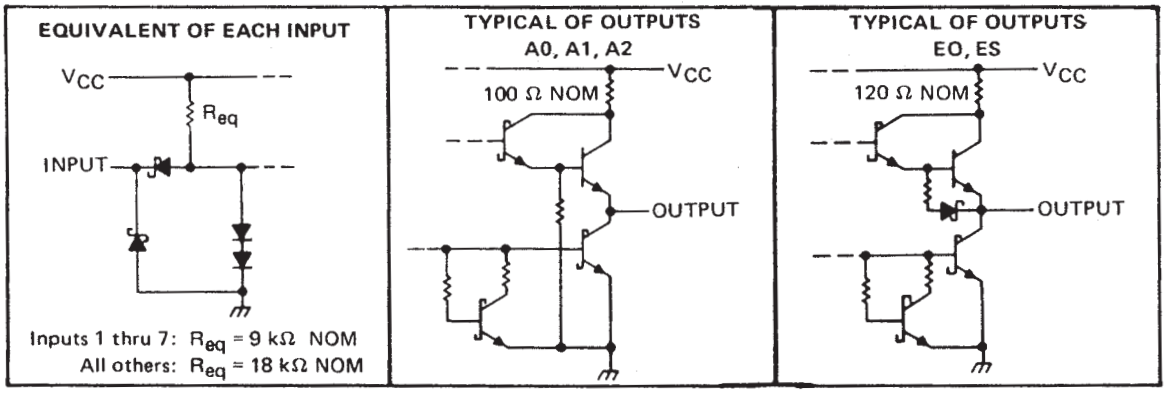
†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematic of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS348 . . . . . −55°C to 125°C
SN74LS348 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS348			SN74LS348			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}	A0, A1, A2			−1			−2.6	mA
	EO, GS			−400			−400	μA
Low-level output current, I_{OL}	A0, A1, A2			12			24	mA
	EO, GS			4			8	mA
Operating free-air temperature, T_A		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS348			SN74LS348			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
V_{OH}	High-level output voltage	A0, A1, A2	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL}max	I_{OH} = −1 mA	2.4	3.1					V
		EO, GS		I_{OH} = −2.6 mA				2.4	3.1		
				I_{OH} = −400 μA	2.5	3.4		2.7	3.4		
V_{OL}	Low-level Output voltage	A0, A1, A2	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL}max	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 24 mA					0.35	0.5	
		EO, GS		I_{OL} = 4 mA		0.25	0.4		0.25	0.4	
				I_{OL} = 8 mA					0.35	0.5	
I_{OZ}	Off-State (high-impedance state) output current	A0, A1, A2	V_{CC} = MAX, V_{IH} = 2 V	V_O = 2.7 V			20			20	μA
				V_O = 0.4 V			−20			−20	
I_I	Input current at maximum input voltage	Inputs 1 thru 7	V_{CC} = MAX,	V_I = 7 V			0.2			0.2	mA
		All other inputs					0.1			0.1	
I_{IH}	High-level input current	Inputs 1 thru 7	V_{CC} = MAX,	V_I = 2.7 V			40			40	μA
		All other inputs					20			20	
I_{IL}	Low-level input current	Inputs 1 thru 7	V_{CC} = MAX,	V_I = 0.4 V			−0.8			−0.8	mA
		All other inputs					−0.4			−0.4	
I_{OS}	Short-circuit output current§	Outputs A0, A1, A2	V_{CC} = MAX		−30		−130	−30		−130	mA
		Outputs EO, GS			−20		−100	−20		−100	
I_{CC}	Supply current		V_{CC} = MAX, See Note 2	Condition 1		13	25		13	25	mA
				Condition 2		12	23		12	23	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.

NOTE 2: I_{CC} (condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open. I_{CC} (condition 2) is measured with all inputs and outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	1 thru 7	A0, A1, or A2	In-phase output	C_L = 45 pF, R_L = 667 Ω, See Note 3		11	17	ns
t_{PHL}						20	30	
t_{PLH}	1 thru 7	A0, A1, or A2	Out-of-phase output			23	35	ns
t_{PHL}						23	35	
t_{PZH}	EI	A0, A1, or A2				25	39	ns
t_{PZL}						24	41	
t_{PLH}	0 thru 7	EO	Out-of-phase output	C_L = 15 pF R_L = 2 kΩ, See Note 3		11	18	ns
t_{PHL}						26	40	
t_{PLH}	0 thru 7	GS	In-phase output			38	55	ns
t_{PHL}						9	21	
t_{PLH}	EI	GS	In-phase output			11	17	ns
t_{PHL}						14	36	
t_{PLH}	EI	EO	In-phase output			17	26	ns
t_{PHL}						25	40	
t_{PHZ}	EI	A0, A1, or A2		C_L = 5 pF R_L = 667 Ω		18	27	ns
t_{PLZ}						23	35	

† t_{PLH} = propagation delay time, low-to-high-level output
t_{PHL} = propagation delay time, high-to-low-level output
t_{PZH} = output enable time to high level
t_{PZL} = output enable time to low level
t_{PHZ} = output disable time from high level
t_{PLZ} = output disable time from low level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

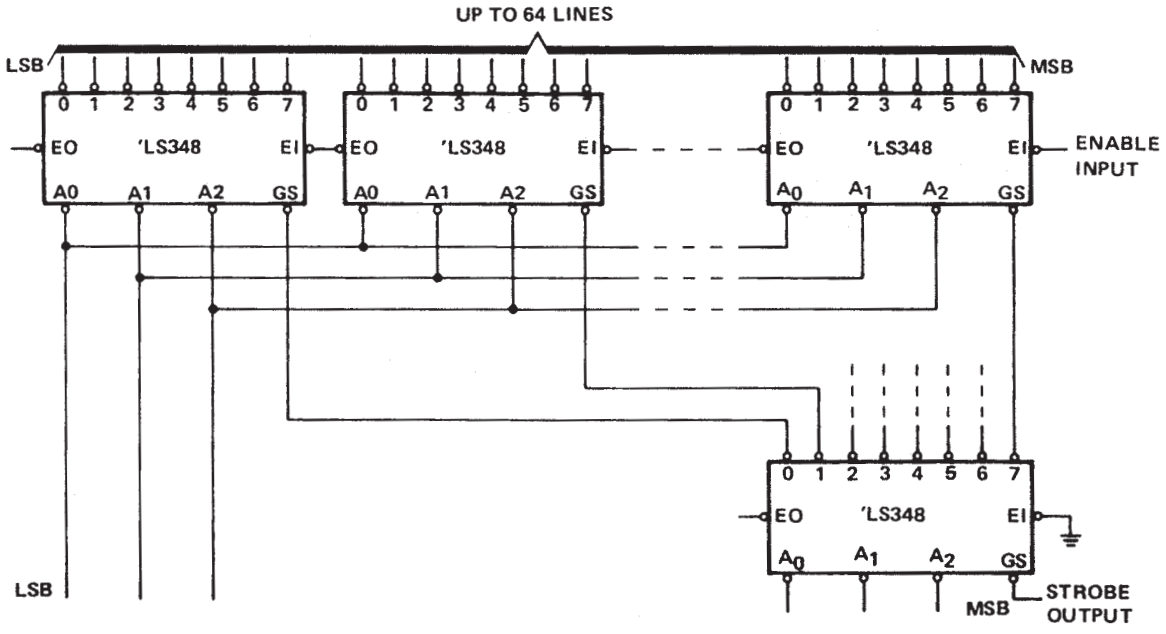


FIGURE 1–PRIORITY ENCODER WITH UP TO 64 INPUTS.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/36002B2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
JM38510/36002BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS348D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS348NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS348FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS348W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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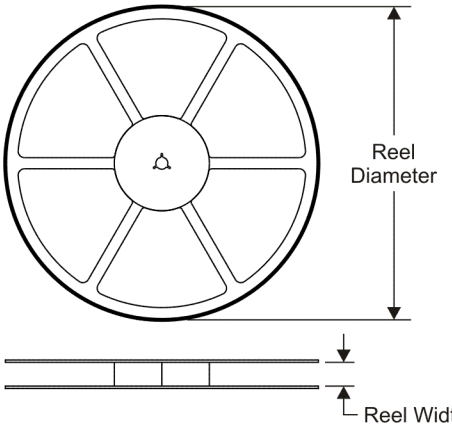
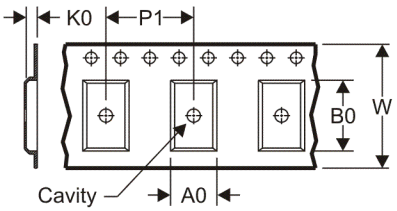
TAPE AND REEL INFORMATION

REEL DIMENSIONS

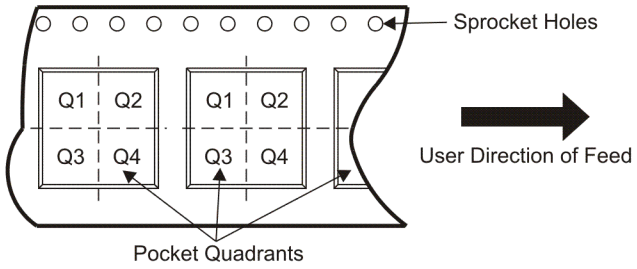


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

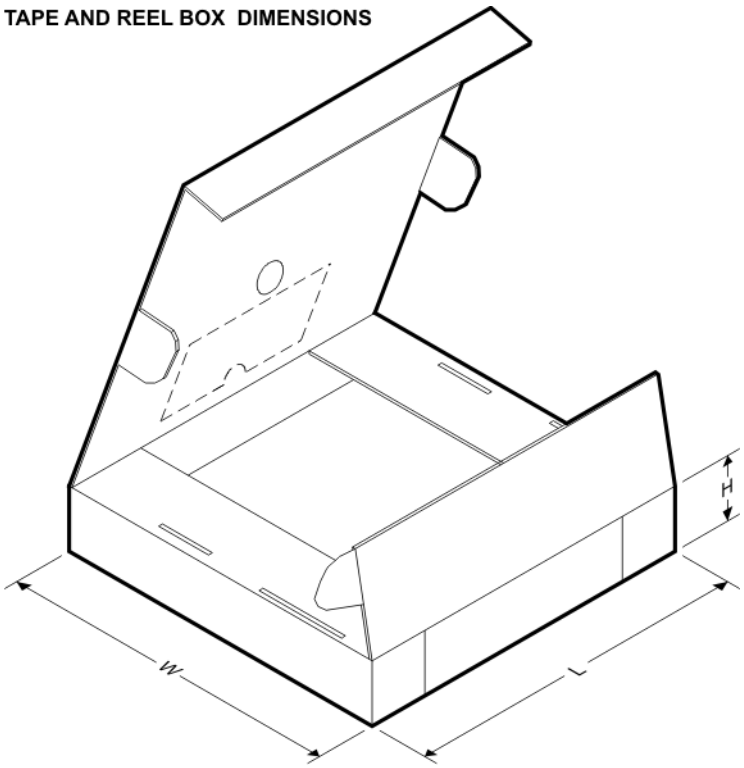
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS348DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS348NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



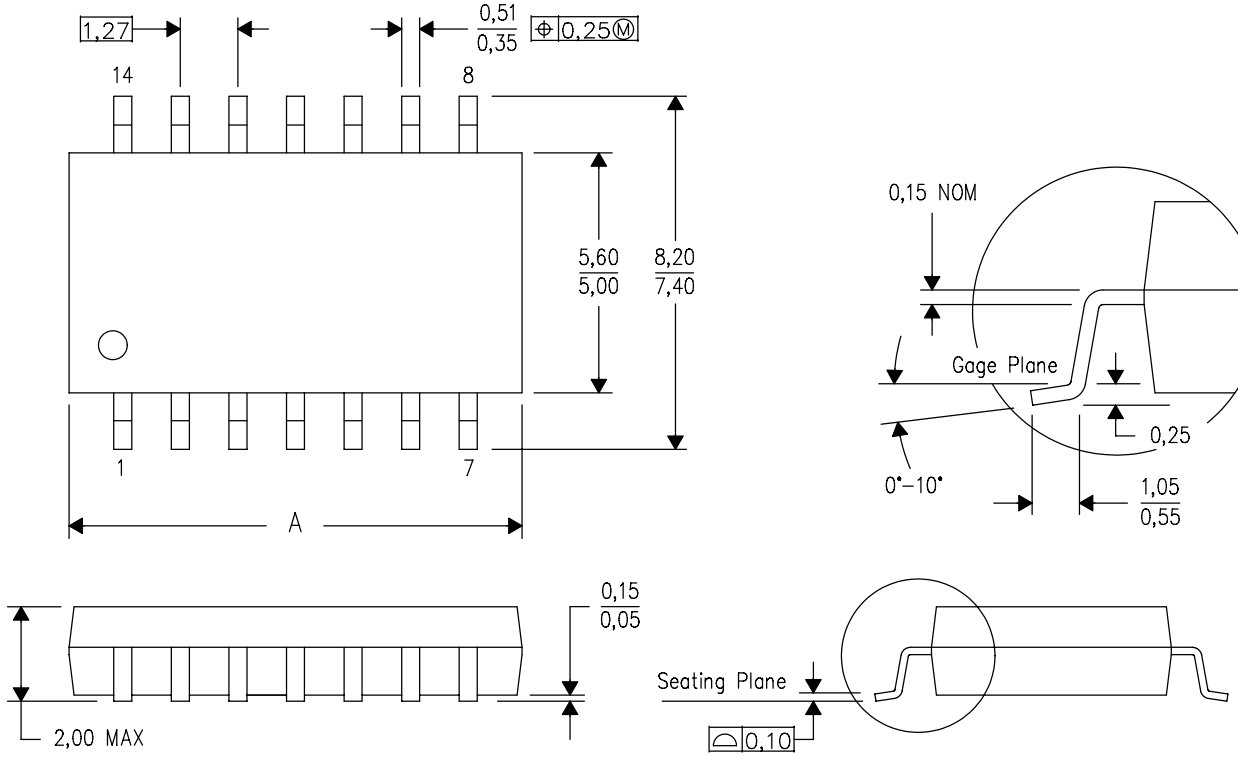
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS348DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS348NSR	SO	NS	16	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

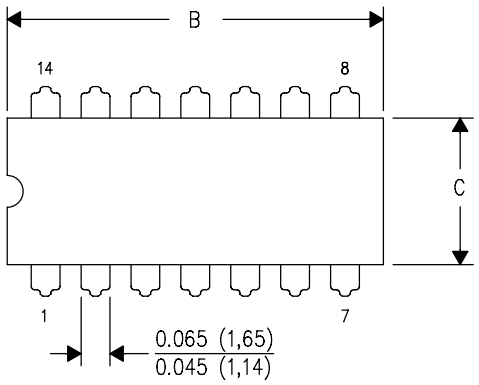
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

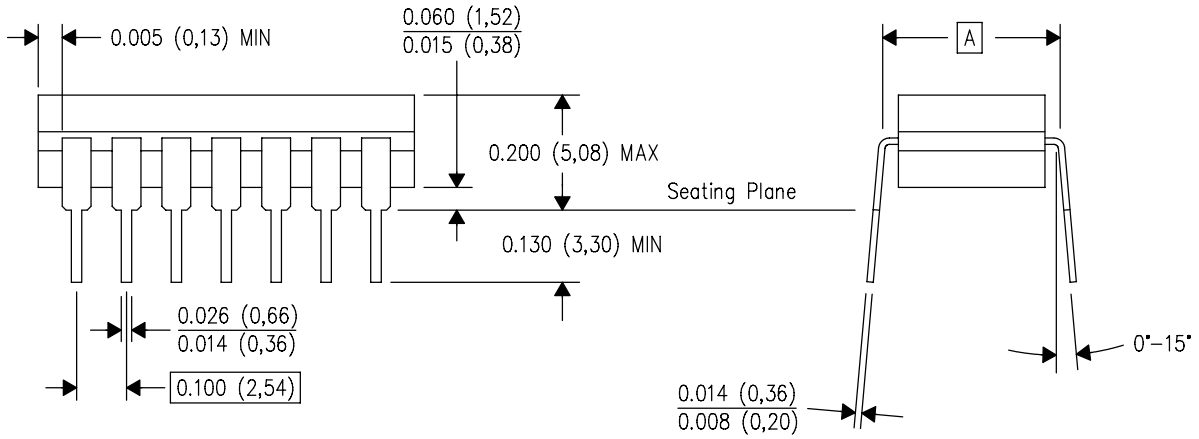
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

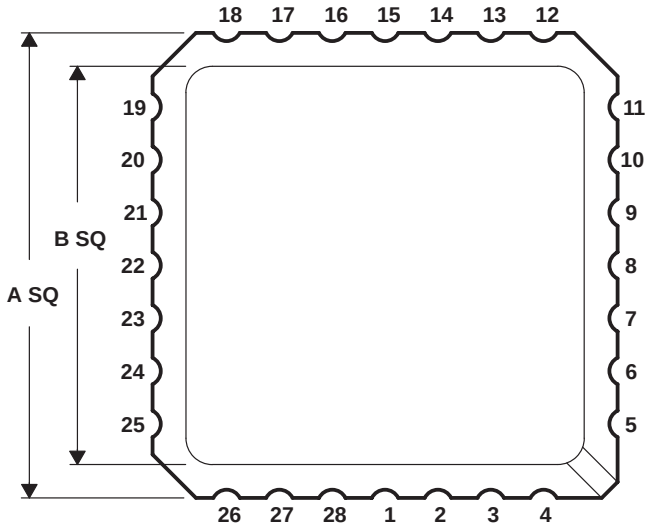


4040083/F 03/03

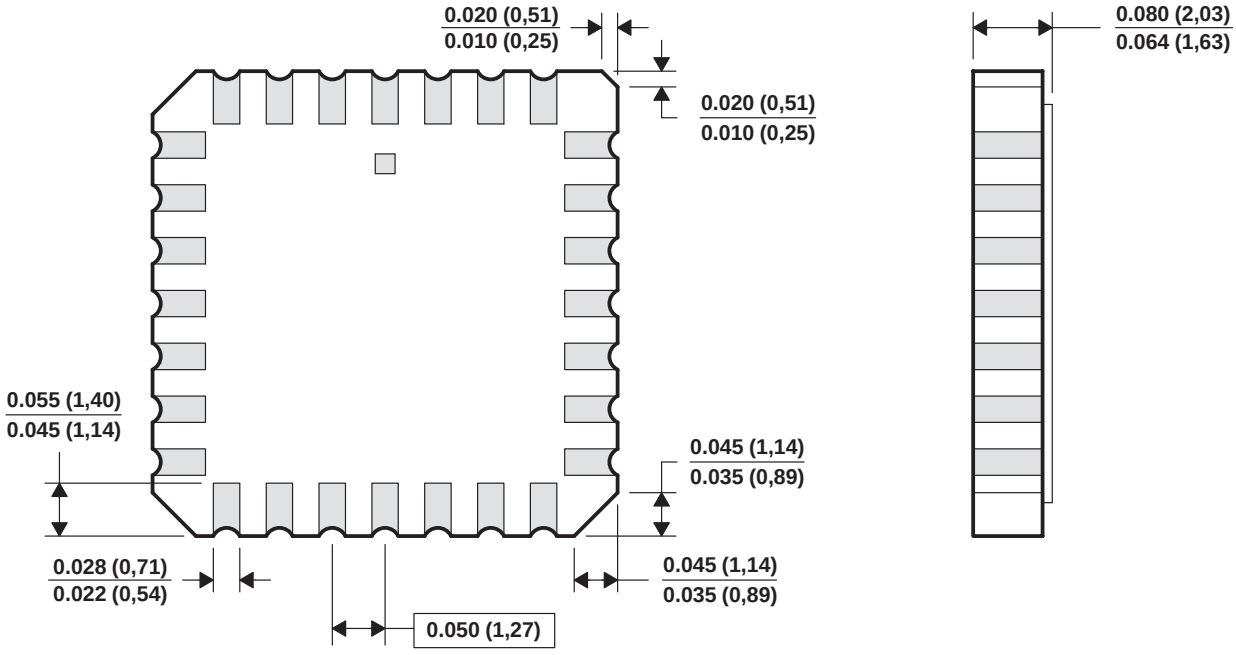
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



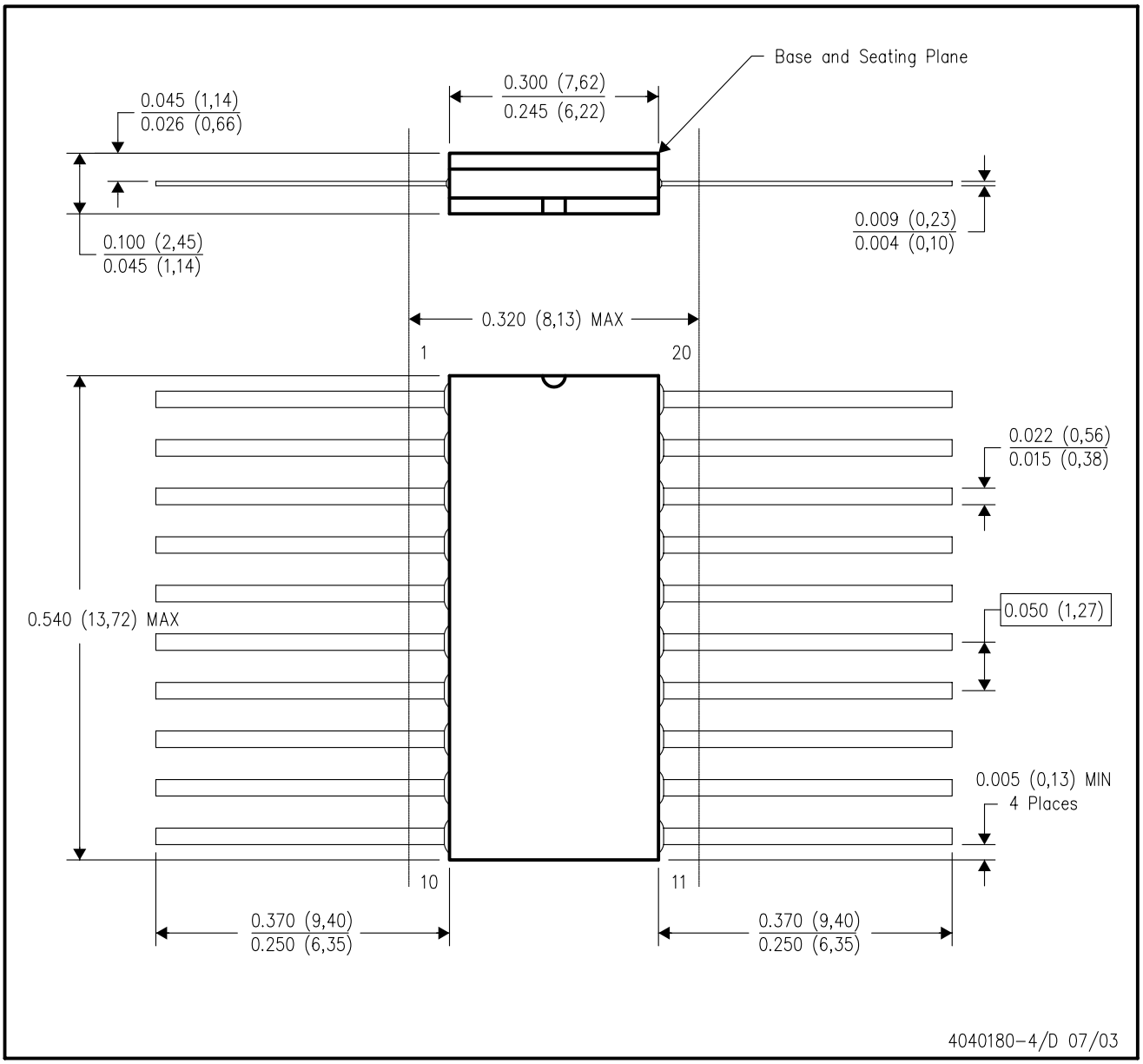
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 10/96

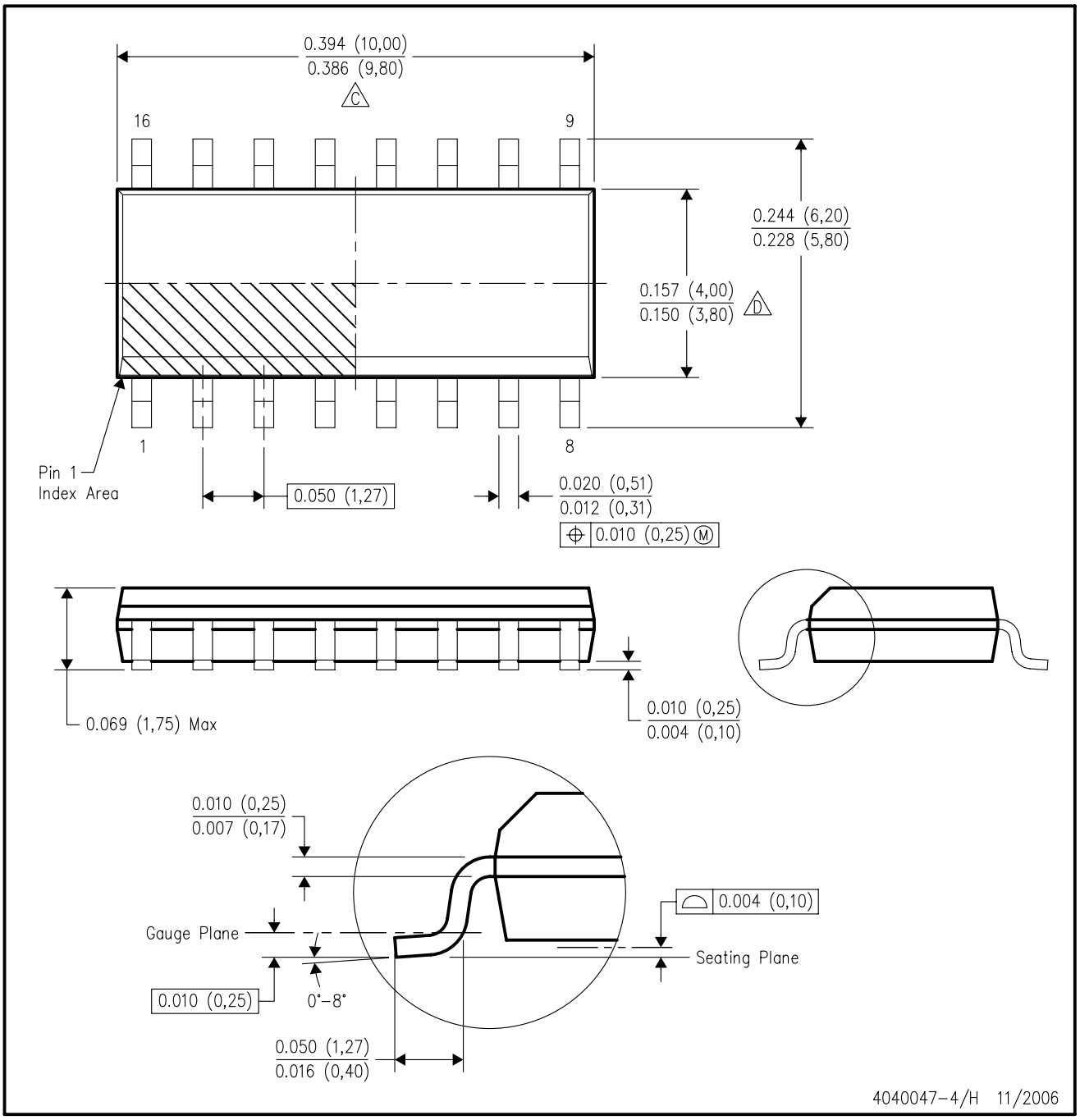
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

W (R–GDFP–F20) CERAMIC DUAL FLATPACK



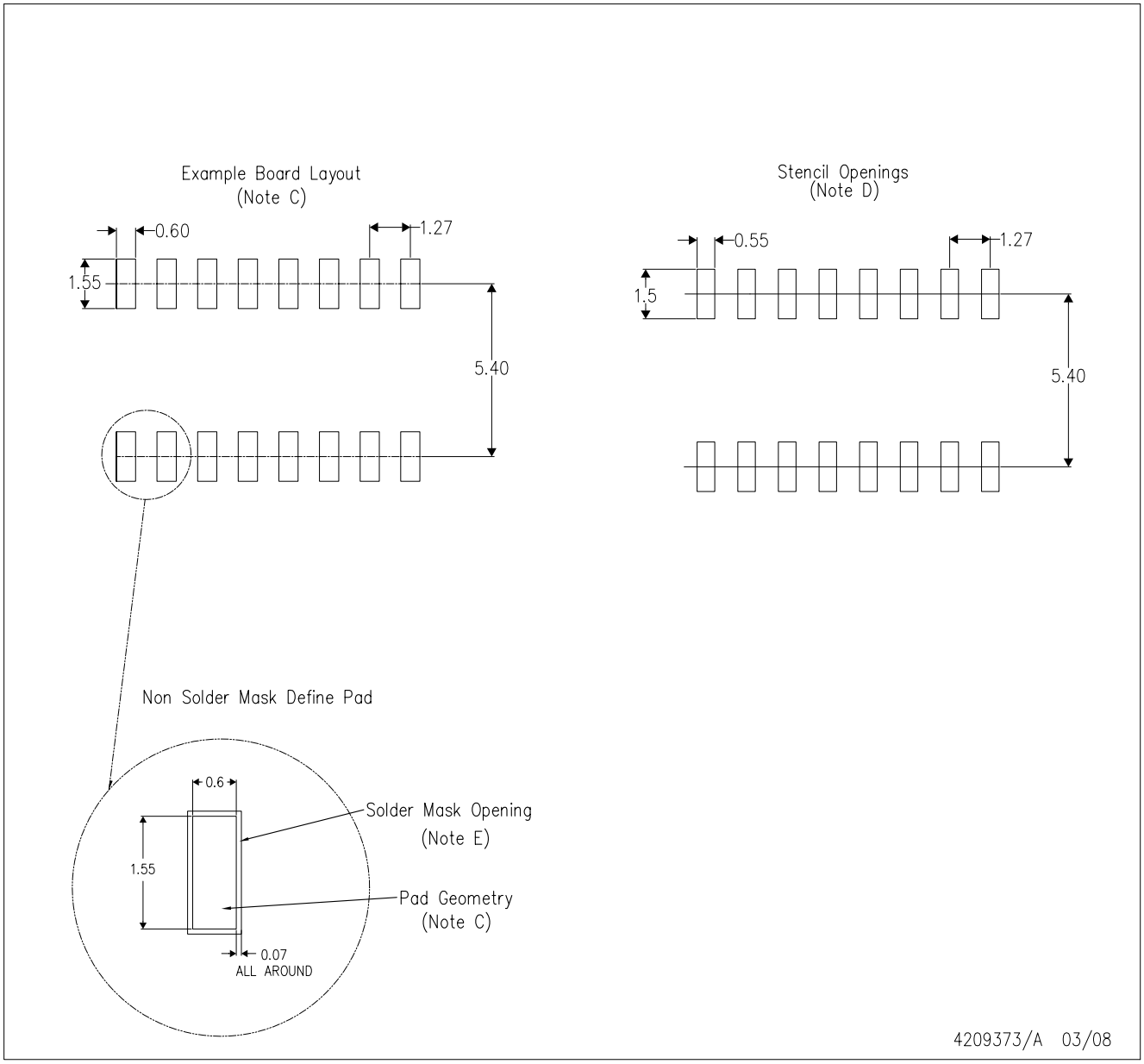
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within Mil–Std 1835 GDFP2–F20

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

D(R–PDSO–G16)

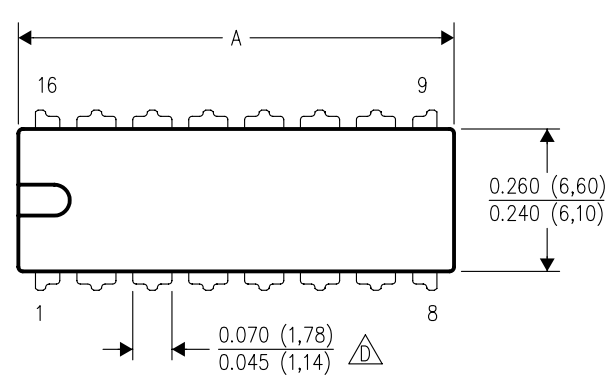


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

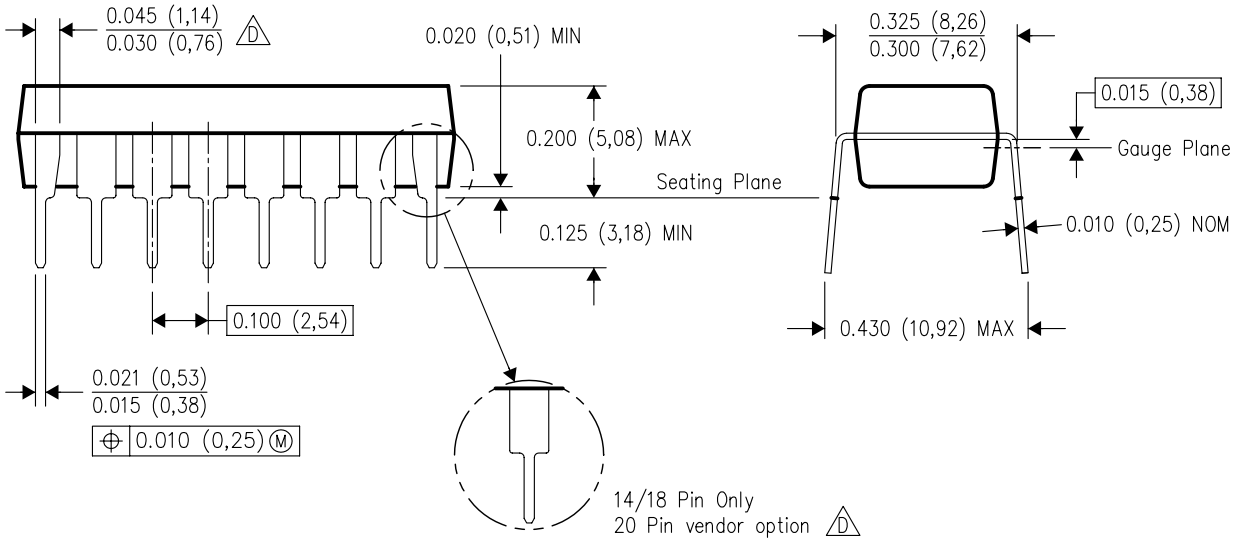
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.